

ABSTRACT OF THE DISCLOSURE

A device and a method for fabricating said device provides a semiconductor light-emitting element having an electrode and a protective film layer that is sealed with an insulating resin, which is hardened at high temperature. After completion of the hardening process, the semiconductor light-emitting element is heat treated in an atmosphere of normal or higher humidity. Preferably, the heat treatment is performed at a temperature of 60°C or higher in an atmosphere having an absolute humidity of 10 KPa or higher. When the heat treatment is performed at or above 10 KPa, the heat treatment can be completed within a shorter timeframe in comparison to such a device heat treated at an absolute humidity of less than 10 kPa.